



DA2J10700L

Silicon epitaxial planar type

For high speed switching circuits
 DA3X107K in SMini2 type package

■ Features

- High reverse voltage VR
- Small reverse current IR
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: B1

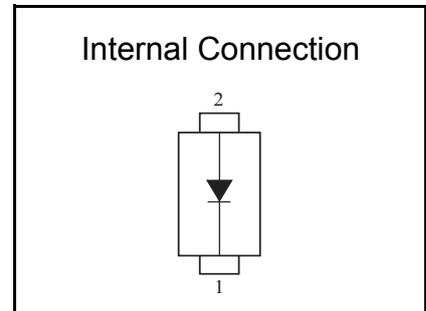
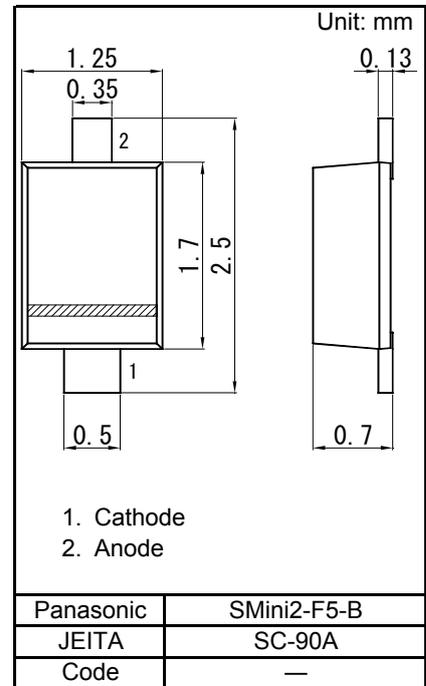
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	300	V
Repetitive peak reverse voltage	VRRM	300	V
Forward current (Average)	IF(AV)	100	mA
Repetitive peak forward current	IFRM	225	mA
Non-repetitive peak forward surge current *1	IFSM	500	mA
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

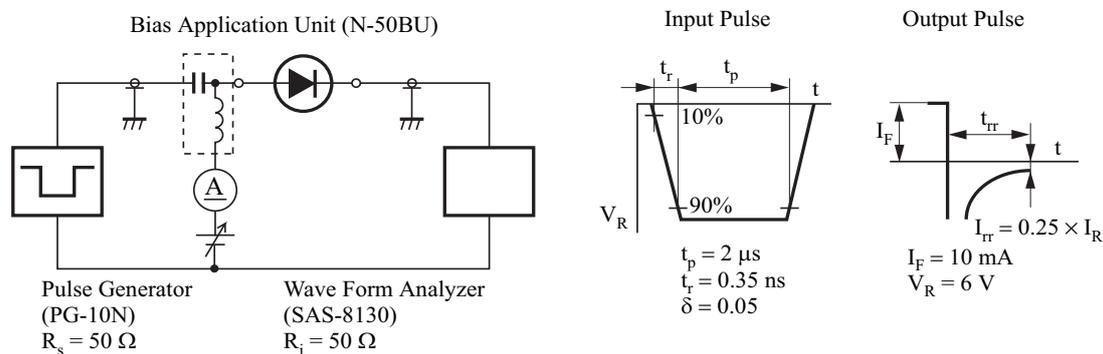
Note) *1: t = 1 s



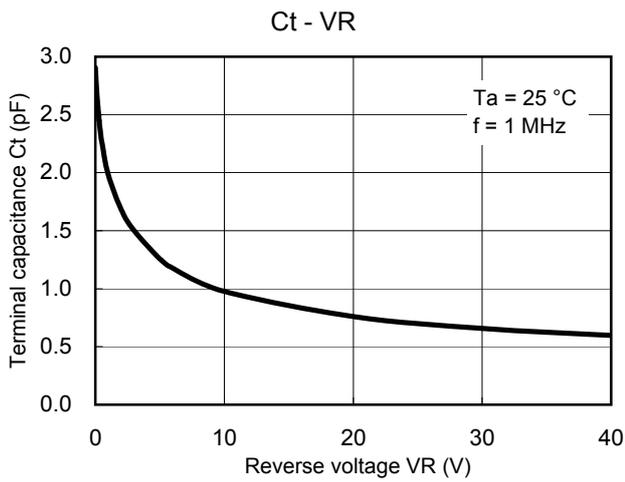
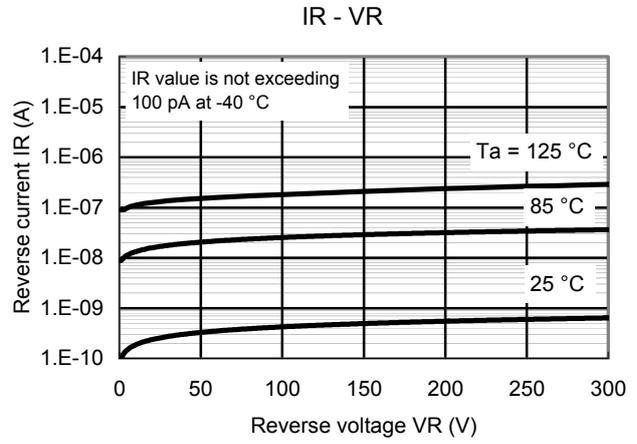
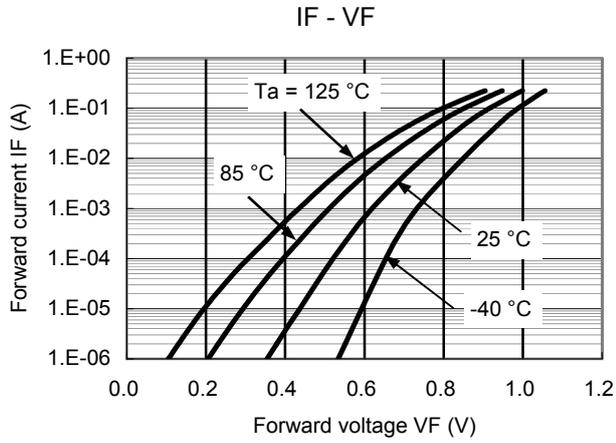
■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA			1.2	V
Reverse current	IR	VR = 300 V			1.0	μA
Terminal capacitance	Ct	VR = 6 V, f = 1 MHz			3.0	pF
Reverse recovery time *1	t _{rr}	IF = 10 mA, VR = 6 V I _{rr} = 0.25 x IR			60	ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 2. Absolute frequency of input and output is 20 MHz.
 3. *1: t_{rr} test circuit

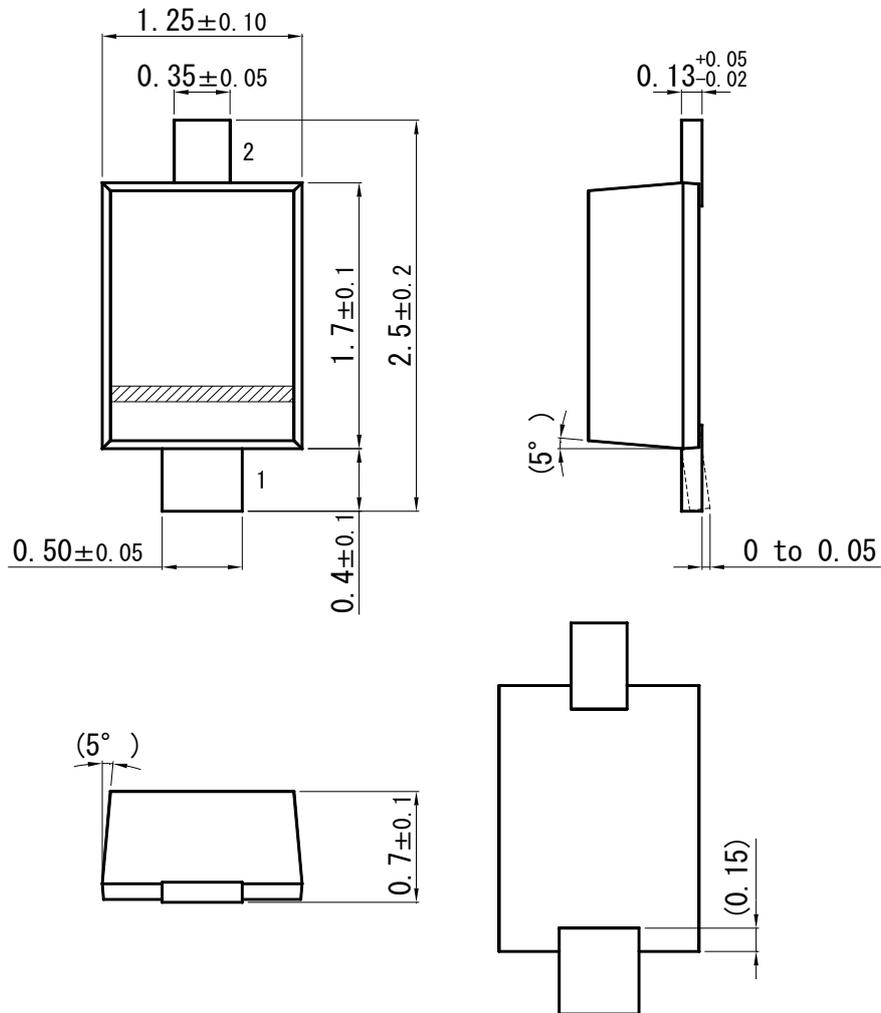


Technical Data (reference)

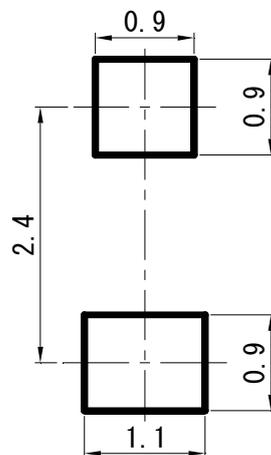


SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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